PCB Part No: 5516011936-003 REV A LMH730216 Rev D

FABRICATION NOTES: UNLESS OTHERWISE SPECIFIED

- 1. MATERIAL: PER IPC-4101/24
 - A. LAMINATE: TYPE GFN, GRADE A, CLASS 2, AND TYPE FR-4
 - B. ONE OUNCE FINISHED: HALF OUNCE BASE COPPER PLATED UP TO 1 OUNCE, OUTSIDE LAYERS.
 - C. BOARD THICKNESS IS MEASURED INCLUDING TOP AND BOTTOM SIDES FINISHED COPPER. ANY TIN, OR GOLD PLATING. SOLDERMASK AND SILKSCREEN LEGEND MUST NOT BE INCLUDED IN FINISHED BOARD THICKNESS.
- 2. ETCH TOLERANCES:
 - A. ALL EXTERNAL LAYERS CONDUCTOR WIDTH MUST BE WITHIN +/- .0015 INCH OR +/- 15% OF GERBER DATA, WHICHEVER IS SMALLER.
 - B. ALL INTERNAL LAYERS CONDUCTOR WIDTH MUST BE WITHIN +/- .0010 INCH OR +/- 15% OF GERBER DATA, WHICHEVER IS SMALLER.
- 3. BOARD MUST BE NC DRILLED USING DRILL DATA SUPPLIED.
- 4. DRILL TOLERANCES AND HOLE SIZES ARE FOR FINISHED BOARD: ALL PLATED THROUGH HOLES TO .080 INCH ARE +/- .003 INCH. ALL PLATED THROUGH HOLES OVER .081 INCH ARE +/- .005 INCH. ALL NON-PLATED THROUGH HOLES ARE +/- .005 INCH.
- 5. ALL HOLES MUST BE REGISTERED WITHIN +/-.003 INCH FROM TRUE POSITION.
- 6. MINIMUM ANNULAR RING MUST BE .002 INCH.
- 7. PLATING:
 - A. PER MIL-C-14550, PLATED THROUGH HOLES MUST BE PLATED WITH .0008 MIN. TO .0012 INCH MAX. THICK COPPER.
 - B. FINISH: IMMERSION GOLD: 2 TO 8 MICROINCHES GOLD OVER 120-240 MICROINCHES OF ELECTROLESS NICKEL.
- 8. WARP AND TWIST OF FINISHED BOARDS MUST NOT EXCEED .007 INCH PER INCH.
- 9. SOLDERMASK: PER IPC-SM-840
 - A. SOLDERMASK BOTH TOP AND BOTTOM SIDES.
 - B. SOLDERMASK MUST CLEAR ALL LANDS SHOWN ON GERBER SOLDERMASK LAYERS.
 - C. COLOR GREEN AND SOLVENT FREE.
 - D. LIQUID PHOTO-IMAGEABLE MUST BE .0002 MIN. TO .0008 MAX. INCH THICK MEASURED OVER COPPER PLATING.
- 10. SILKSCREEN TOP SIDE USING A GLOSSY WHITE, NONCONDUCTIVE, EPOXY BASED INK. NO SILKSCREEN ALLOWED ON TIN-LEAD OR GOLD AREAS, ON PADS OR IN HOLES.
- 11. ROUTE BOARD OUTLINE, PER DRAWING DIMENSIONS.
- 12. VENDOR MUST ENTER VENDOR'S IDENTITY, DATE CODE AND ANY OTHER IDENTIFICATION MARKS ON ARRAY RAILS.
- 13. OTHER VENDOR NOMENCLATURE OR MARKINGS SHOULD NOT BE ETCHED OR SILKSCREENED ON BOARD WITHOUT PRIOR PERMISSION.
- 14. ALL VENDOR IN-PROCESS MARKINGS, QA STAMPS, ETC. MUST BE PLACED ON THE BOTTOM SIDE OF BOARD.
- 15. FINISHED BOARD MUST MEET UL94V-0 RATING AND RoHS COMPLIANCE.
- 16. DOCUMENTATION THAT MUST BE DELIVERED WITH BOARDS: A. RoHS CERTIFICATE OF COMPLIANCE.
- 17. TRACE WIDTH AND LAYER SPACING MAY BE CHANGED TO ACCOMMODATE FABRICATION PROCESS BUT PRIOR APPROVAL IS REQUIRED BEFORE TRACE WIDTH OR LAYER SPACING CHANGES ARE MADE.